Abstract

A semiconductor processing apparatus (116) comprises an inner sidewall (116d) and an outer sidewall (116b), both of which are in a cylindrical shape, a flange (116a) extending outwards from the outer sidewall, a shield plate (116c) between the inner sidewall and the outer sidewall, wherein the outer sidewall extends upwardly perpendicularly or along an angle from the upper surface of the flange for a first distance (116g) and extends downwards perpendicularly or along an angle from the shield plate for a second distance (116f); the inner sidewall extends upwardly perpendicularly or along an angle from the shield plate for a third distance and extends downwards perpendicularly or along an angle from the shield plate for a fourth distance (116e); the shield plate has a stepped structure, and rows of apertures (170) distributed uniformly are provided on an upper stepped surface and a lower stepped surface thereof.